



**ENGINEERED
CONDUCTIVE
MATERIALS**

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COPPER FLEX CIRCUITS

Product Designation	Description	Typical Cure	Electrical Resistance Ohms/Sq/Mil
CI-1031-7	Silver thermoset ink, highly conductive for silver jumpers or EMI/RFI printed shield pattern	10 Min. @ 300°F	<0.010
CI-2002	Carbon ink for jumpers, resistors, shunts, or copper top-coat	10 Min. @230° F.	<20.0
DB-1501	One component stencil print silver adhesive	<6 Min @285° F	0.0004 ohm-cm
DB-1527	Two component needle dispense silver SMT adhesive	5 Min @ 120° C	0.003 ohm-cm
DI-7008 A/B	Solvent based dielectric	5-10 Min. @ 230°F	>1,000 Mega ohms
DI-7503	Flexible UV curable dielectric	450 millijoules per Square Centimeter	>1,000 Mega ohms
EC-9519	UV curable encapsulant, flexible	450 millijoules per Square Centimeter	>1,000 Mega ohms